

Mek SpectorBOX Bottom Up and Top Down Modular AOI System

√ Optimized for THT Components- and Post Wave and Selective Soldering Inspections

AOI Solution For Wave & Selective Soldering Of THT & SMT Components

√ Bottom-up and/or Top-down Inspection

Inspects PCB's From Below a Conveyer Belt or Chain

√ Solder Frame Compatible

Designed to Inspect PCB's Inside Solder Frames Directly From The Conveyer

√ Ultra Slim Design Inspects Down To 280mm Above Factory Floor Save Production Space! Fits Below Existing Return and/or Feed Conveyers

√ Modular Inspection Possibilities: Bottom, Top or Top + Bottom Possibility to Combine Two SpectorBOX Systems For Simultaneous Top+Bottom AOI

√ Main Frame Compatibility

Multiple 3rd Party Turn Key Solutions Readily Available. Spector-BOX Systems Fit Conveniently Inside these Main Frames

√ Up to 18 Cameras

Choose between 1 or 9 camera's per inspection side (up to 18 cameras in Top+Bottom configuration)

√ In Z-Axis Moving Optical Head(s)

Focus and Position Optimally For Varying PCB Distances Or Warpage (Applicable To Certain Models With Z-Axis)

√ General Purpose I/O

Configurable I/O to Be Controlled By Existing PCB Handling Systems

√ Post Defect Classification and Reporting Scenarios

Inspect your PCB's Automatically Now, Classify/Report Defects Later Whenever Convenient

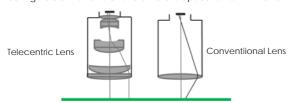




1. Bottom Up Features:

The Mek SpectorBOX bottom up modular AOI is optimized for the inspection of THT solder joints and detection of solder bridges and solder balls. It is designed to inspect PCB's inside solder frames directly from the conveyor system. With it's totally newly developed mechanical platform, it is the only modular AOI in the market that can be equipped with 9 cameras: 1 top and 8 side cameras. The bottom up SpectorBOX is configurable with one of two different optical units: FDLz and FDAz.

	Angular Camera's	Z-Axis
FDLz	NO	YES
FDAz	YES	YES



High grade Telecentric Lens

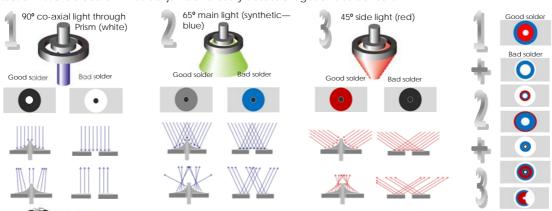
Parallel image over the whole sensor/lens Field of View — No parallax effect

Large pixel image capturing sensor

18,8µ² pixel size — smooth and detailed image with great dynamic range — Japanese built

Omnidirectional multi angle, multi color LED lighting

3D color profile of solder meniscus — accurate defect decision by the software algorithms — Detect all visual defects of THT solder joints and easily detect bridges and solder balls



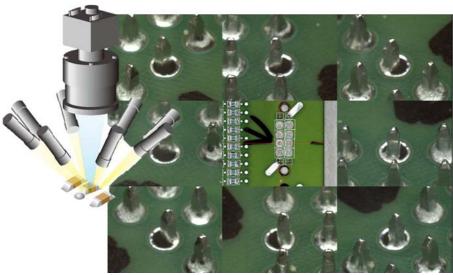


In Height Adjustable Optical Head

In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness - PCB Warp Compensation — Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

8x Angular Side Sensors (Only available for FDA and FDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database



Powerful algorithms for

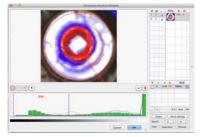




Dedicated algorithms for solder balls detection

Histogram Analysis algorithms

Condition based decision — Tolerances can be set tightly - Close to zero false alarms







2. Top Down Features:

The Mek SpectorBOX Top Down modular AOI is optimized for the inspection of THT components to find any visual defect like prsence/absence, wrong polarity, colour, type, bent pins etc. It has a top clearance of 130mm (5.12") so inspection can be done even when the tallest components are placed. It is designed to inspect PCB's inside solder frames directly from the conveyor system. The SpectorBOX Top Down module can be equipped with one top camera and 8 wide field of view side camera's. Available optical units are FWz and FWAz.

	Angular Camera's	Z-Axis
FWz	NO	YES
FWAz	YES	YES



Large pixel image capturing sensor

 $18,8\mu^2$ pixel size — smooth and detailed image with great dynamic range — Japanese built

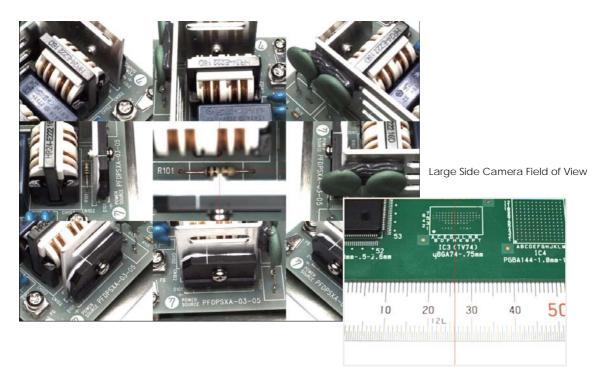


In Height Adjustable Optical Head

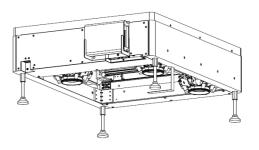
In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Reliable text and/or polarity inspection on tall components — Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

8x Angular Side Sensors (Only available for the FWAz model)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database











Bottom Up

FDL

	SpectorBOX FDLz 550			
Maximum PCB Size	550x520mm (21.7" x 20.5")			
Characteristics				
Product type	Automatic Optical Inspector			
Camera movement	X+Y Dire	ection		
PCB movement	Statio	nary		
Parts inspection	Soldering, Bridg	es, Solder Balls		
Imaging principle	Synthetic Imaging, Spectra	Analysis, Greyscale limits		
Imaging parameters	Brightness, Hue, Sa	turation via Filters		
Specifications				
Main Camera type	Digital with C	CameraLink		
Main Camera Field Of View/ Resolution	36x20mm/18.75µm с	or 19.2x10.8mm/10µ		
Lens	Telecentric lens with built i	n prism for DOAL Lighting		
Lighting system	Omnidirectional Triple LED rings: Side, Main, Line Sourced DOAL Diffused On Axis Lighting (Coaxial))			
Minimum inspection object size	80μ (3.15 mils)			
Positioning accuracy	Pixel related Feedback Loop			
Component clearance	+40mm	(1.57")		
Side Cameras	No side c	cameras		
Z-Axis movement range	60mm (2.4")			
Movement speed	720mm/s			
Inspection capacity typical	1500cps/min			
Mains	100-240 Va	ac / 150W		
Interfacing				
Control PC type	Apple MacMini (or higher) with Ma			
Control interface	US			
Data interface	Camer			
Communication	General Purpo	ose I/O, RS232		
General				
Operating temperature	15-30 degr C (59-86 degr F)			
Operating humidity	15-80 % RH			
External size	W750 x D842 x H256 (29.5" x 33.2" x 10.1")	W900 x D1056 x H251 (35.5" x 41.6" x 9.9")		
Weight	50kg (110lbs)	100kg (220lbs)		
Weight	ouky (Truius)	TOURY (ZZUIDS)		

Represented/Distribut	ed by:		



Bottom Up

FDA

	SpectorBOX FDAz 550		
Maximum PCB Size	550x520mm (21.7" x 20.5")		
Characteristics			
Product type	Automatic Optical Inspector		
Camera movement	X+Y Dir	ection	
PCB movement	Static	onary	
Parts inspection	Soldering, Bridg	jes, Solder Balls	
Imaging principle	Synthetic Imaging, Spectra	l Analysis, Greyscale limits	
Imaging parameters	Brightness, Hue, Sa	aturation via Filters	
Specifications			
Main Camera type	Digital with (CameraLink	
Main Camera Field Of View/ Resolution	36x20mm/18.75µm (or 19 2x10 8mm/10u	
Lens			
20110	Telecentric lens with built in prism for DOAL Lighting		
Lighting system	Omnidirectional Triple LED rings: Side, Main, Line Sourced DOAL Diffused On Axis Ligh (Coaxial))		
Minimum inspection object size	80μ (3.15 mils)		
Positioning accuracy	Pixel related Feedback Loop		
Component clearance	+30mm (1.2")		
Side Cameras	8x Digital with Cameral	ink in 45/45 orientation	
Z-Axis movement range	60mm (2.4")		
Movement speed	720mm/s		
Inspection capacity typical	1500cg	os/min	
Mains	100-240 Va	ac / 150W	
Interfacing			
Control PC type	Apple MacMini (or higher) with Ma	ac OSX and Thunderbolt interface	
Control interface	US	SB	
Data interface	Came	raLink	
Communication	General Purpo	ose I/O, RS232	
General			
Operating temperature	15-30 degr C (59-86 degr F)		
Operating humidity	15-80 % RH		
	W750 x D842 x H256 W900 x D1056 x H251		
External size	(29.5" x 33.2" x 10.1")	(35.5" x 41.6" x 9.9")	
Weight	50kg (110lbs)	100kg (220lbs)	

Represented/Distributed by:		





FWz

	SpectorBOX FDLz 550			
Maximum PCB Size	550x520mm (21.7" x 20.5")			
Characteristics				
Product type	Automatic Optical Inspector			
Camera movement	X+Y Dire	ection		
PCB movement	Statio	nary		
Parts inspection	Presence/Absence, Type, P	olarity, Colour, Text, Offset		
Imaging principle	Synthetic Imaging, Spectra	Analysis, Greyscale limits		
Imaging parameters	Brightness, Hue, Sa	turation via Filters		
Specifications				
Main Camera type	Digital with C	CameraLink		
Main Camera Field Of View/	36x20mm/18.75µm or 19.2x10.8mm/10µ			
Lighting system	Omnidirectional Single	e Source White Light		
Minimum inspection object size	80μ (3.15 mils)			
Positioning accuracy	Pixel related Feedback Loop			
Component clearance	+130mm (5.12")			
Side Cameras	No side cameras			
Side Cameras Field of View	N/A	A		
Z-Axis movement range	60mm (2.4")			
Movement speed	720mm/s			
Inspection capacity typical	1500cps/min			
Mains	100-240 Vac / 150W			
Interfacing				
Control PC type	Apple MacMini (or higher) with Ma	c OSX and Thunderbolt interface		
Control interface	USB			
Data interface	Camer			
Communication	General Purpo	se I/O, RS232		
General				
Operating temperature	15-30 degr C (59-86 degr F)			
Operating humidity	15-80	% RH		
External size	W750 x D842 x H256 (29.5" x 33.2" x 10.1")	W900 x D1056 x H251 (35.5" x 41.6" x 9.9")		
Weight	50kg (110lbs)	100kg (220lbs)		

Represented/Distributed by:		





FWA

	SpectorBOX FDAz 550			
Maximum PCB Size	550x520mm (21.7" x 20.5")			
Characteristics				
Product type	Automatic Optical Inspector			
Camera movement	X+Y Dire	ection		
PCB movement	Statio	nary		
Parts inspection	Presence/Absence, Type, P	olarity, Colour, Text, Offset		
Imaging principle	Synthetic Imaging, Spectra	Analysis, Greyscale limits		
Imaging parameters	Brightness, Hue, Sa	turation via Filters		
Specifications				
Main Camera type	Digital with 0	CameraLink		
Main Camera Field Of View/ Resolution	36x20mm/18.75µm с	36x20mm/18.75µm or 19.2x10.8mm/10µ		
Lighting system	Omnidirectional Singl	e Source White Light		
Minimum inspection object size	80μ (3.15 mils)			
Positioning accuracy	Pixel related Feedback Loop			
Component clearance	+130mm (5.12")			
Side Cameras	8x Digital with CameraL	ink in 45/45 orientation		
Side Cameras Field of View	50x39mm (*	1.96x1.54")		
Z-Axis movement range	60mm	60mm (2.4")		
Movement speed	720m	720mm/s		
Inspection capacity typical	1500cp	1500cps/min		
Mains	100-240 Va	ac / 150W		
Interfacing				
Control PC type	Apple MacMini (or higher) with Ma	ac OSX and Thunderbolt interface		
Control interface	US	В		
Data interface	Came	raLink		
Communication	General Purpose I/O, RS232			
General				
Operating temperature	15-30 degr C (59-86 degr F)		
Operating humidity	15-80	% RH		
External size	W750 x D842 x H256	W900 x D1056 x H251		
Weight	(29.5" x 33.2" x 10.1") 50kg (110lbs)	(35.5" x 41.6" x 9.9") 100kg (220lbs)		
weight	Suky (Trubs)	TOURY (2201DS)		

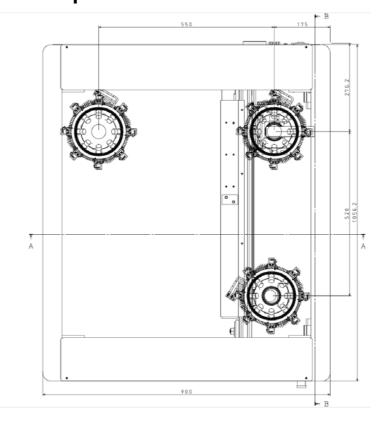
Represented/Distributed by:		

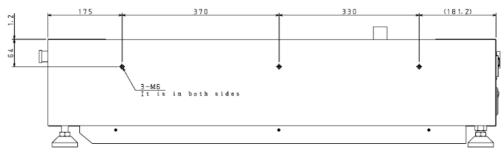


Spector AUX

Bottom Up

FDLz/FDAz







Marantz Electronics Ltd. reserves the right to change the design and specifications without notice. © Mek Europe BV, June 2015

Represented/Distributed by:

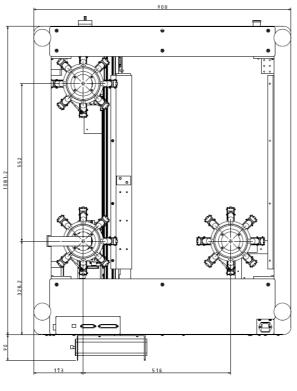


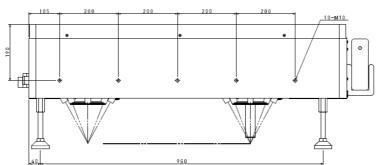
4F North Square I, Yokohama Business Park, 134 Goudo-cho, Hodogayaku, Yokohama, Kanagawa Japan 240-0005 T +81-45-340-5566 info@marantz-mek.co.jp,

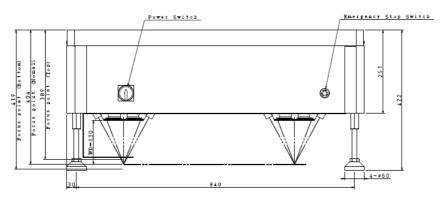
info@marantz-mek.c www.model22x.com

*Epector BIIX*Top Down F

FWz/FWAz







Marantz Electronics Ltd. reserves the right to change the design and specifications without notice. © Mek Europe BV, June 2015

Represented/Distributed by:



Mek Americas LLC 5550 Painted Mirage Rd., STE 320 Las Vegas, NV 89149 T +1 702 818 1706 info@marantz-electronics.com www.marantz-electronics.com

4F North Square I, Yokohama Business Park, 134 Goudo-cho, Hodogayaku, Yokohama, Kanagawa Japan 240-0005 T +81-45-340-5566 info@marantz-mek.co.ip www.model22x.com

Mek Europe BV Polluxstraat 2b 5047 RB Tilburg, Netherlands T+31 40 7114111 info@mek-europe.com www.mek-europe.com